

## Features

- 2427 with integrated high quality constant current IC and RGB LED chip.
- Built-in IC, with high precision of constant current and internal RGB chips spectral processing in advance.
- Single line data transmission (return to zero code).
- Specific Shaping Transmit Technology - number of LED stacked is not restricted.
- Cascading Enhancement Technology - any 2 LED spacing can be up to 10 meters
- Data transfer rate of 750 kbp/s at 30 frames per second.
- RGB output port PWM control can achieve 256 grey level adjustments.
- Upon powering up, IC performs self-inspection then lights connection on the pin B lamp.
- SA-I Anti-interference patent technology for single line data transmission.
- Built-in power supply reverse connect protection module, reversed power input will not damage the IC.

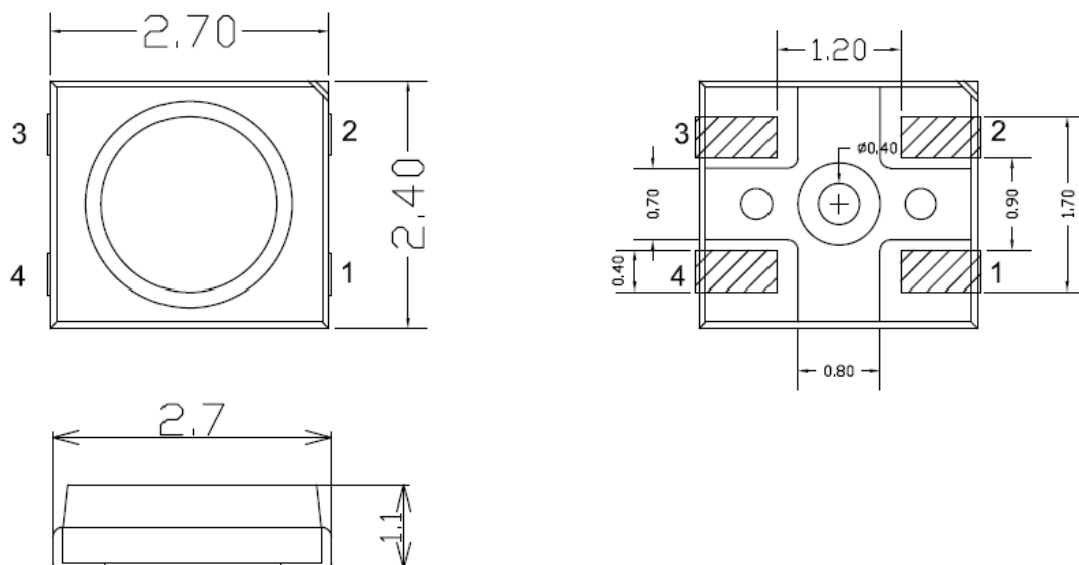
## Description

The IN-PI22TAT5R5G5B is 2.4\*2.7\*1.1mm RGB LED with integrated IC. It is a SMD type LED which can be used in various applications.

## Applications

- Full color LED string light
- LED full color module
- LED guardrail tube
- LED scene lighting
- LED point light
- LED pixel screen
- LED shaped screen

## Package Outline Dimensions & Pin Configuration



**Figure 1. IN-PI22TAT5R5G5B Package Outline Dimensions**

### Pin Configuration

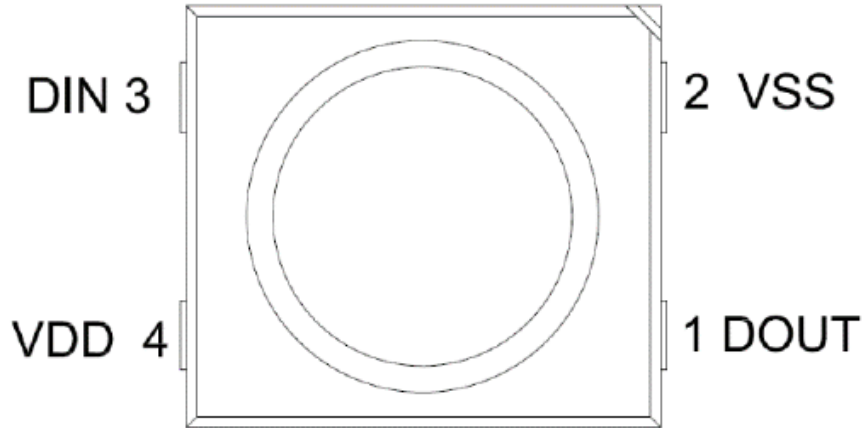


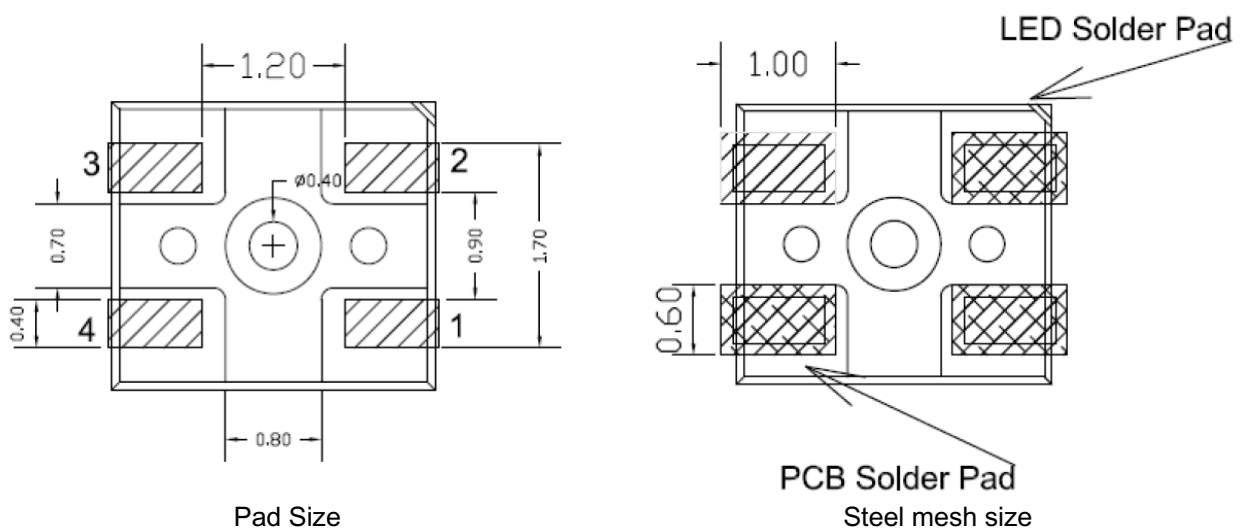
Figure 2. IN- PI22TAT5R5G5B Pin Configuration

Notes:

1. Dimension in millimeter, tolerance is  $\pm 0.1\text{mm}$  unless otherwise noted.

Number	Symbol	Function Description
1	DOUT	Control data signal output
2	VSS	Ground
3	DIN	Control data signal input
4	VDD	Power supply LED

### Soldering Pad Size



**Absolute Maximum Rating** ( $T_a = 25\text{ }^\circ\text{C}$ ,  $V_{SS}=0\text{V}$ )

Parameter	Symbol	Range	Unit
Power supply voltage	$V_{DD}$	+3.5~+5.5	V
Logic input voltage	$V_{IN}$	-0.5 ~VDD+0.5	V
Working temperature	$T_{OPT}$	-45 ~ +85	$^\circ\text{C}$
Storage temperature	$T_{STG}$	-50 ~ +150	$^\circ\text{C}$
ESD pressure(HBM)	$V_{ESD}$	4K	V
ESD pressure(DM)	$V_{ESD}$	200	V

**LED Characteristics** ( $T_A = 25\text{ }^\circ\text{C}$ )

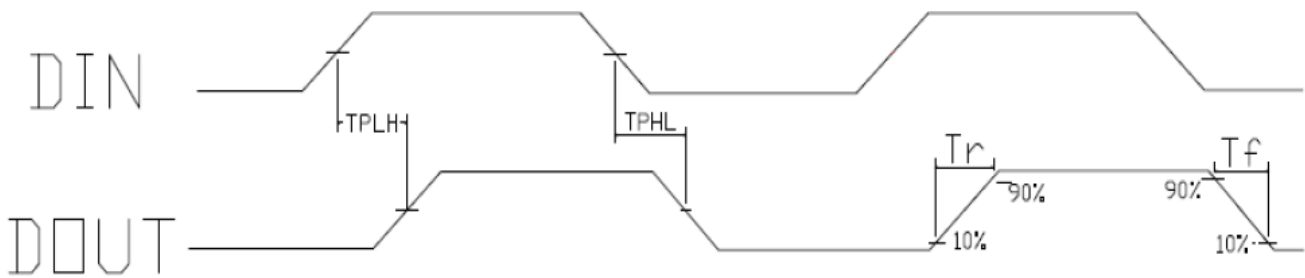
Color	5mA	
	Wavelength(nm)	Light Intensity(mcd)
Red	620-630	100-200
Green	520-535	400-700
Blue	460-475	50-100

**Recommended Operating Ranges** (unless otherwise specified,  $T_A = -20 \sim +70 \text{ }^\circ\text{C}$ ,  $V_{DD} = 4.5 \sim 5.5\text{V}$ ,  $V_{SS} = 0\text{V}$ )

Parameter	Symbol	Min.	Typ.	Max	Unit	Test conditions
Supply voltage	$V_{DD}$	-	5.2	-	V	-
R/G/B port pressure	$V_{DS, MAX}$	-	-	26	V	-
DOUT drive capability	$I_{DOH}$	-	49	-	mA	DOUT connect ground, the maximum drive current
DOUT drive capability	$I_{DOL}$	-	-50	-	mA	DOUT connect +, the largest current
The signal input flip threshold	$V_{IH}$	3.4	-	-	V	$V_{DD} = 5.0\text{V}$
The signal input flip threshold	$V_{IL}$	-	-	1.6	V	$V_{DD} = 5.0\text{V}$
The frequency of PWM	$F_{PWM}$	-	1.2	-	KHZ	-
Static power consumption	$I_{DD}$	-	1	-	mA	-

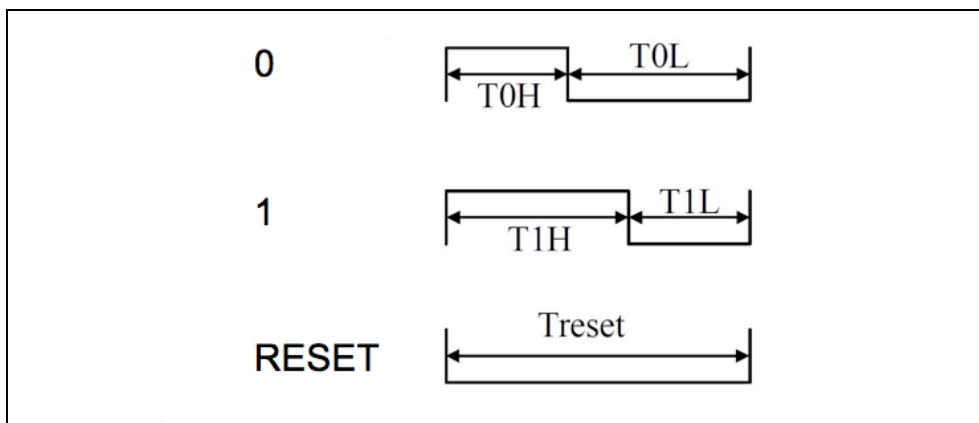
**Switching Characteristics** (unless otherwise specified,  $T_a=25\text{ }^\circ\text{C}$ )

Parameter	Symbol	Min.	Typ.	Max	Unit	Test conditions
The speed of data transmission	$f_{DIN}$	-	800	-	KHZ	The duty ratio of 67% (data 1)
DOOUT transmission delay	$T_{PLH}$	-	-	500	ns	DIN→DOOUT
	$T_{PHL}$	-	-	500	ns	
$I_{OUT}$ Rise/Drop Time	$T_r$	-	100	-	ns	VDS=1.5 VIOUT=13mA
	$T_f$	-	100	-	ns	



**Timing Waveforms**

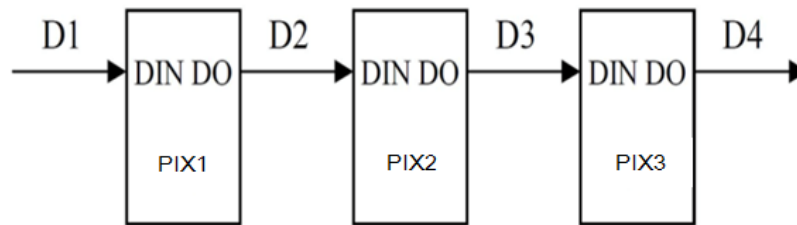
1. Input Code



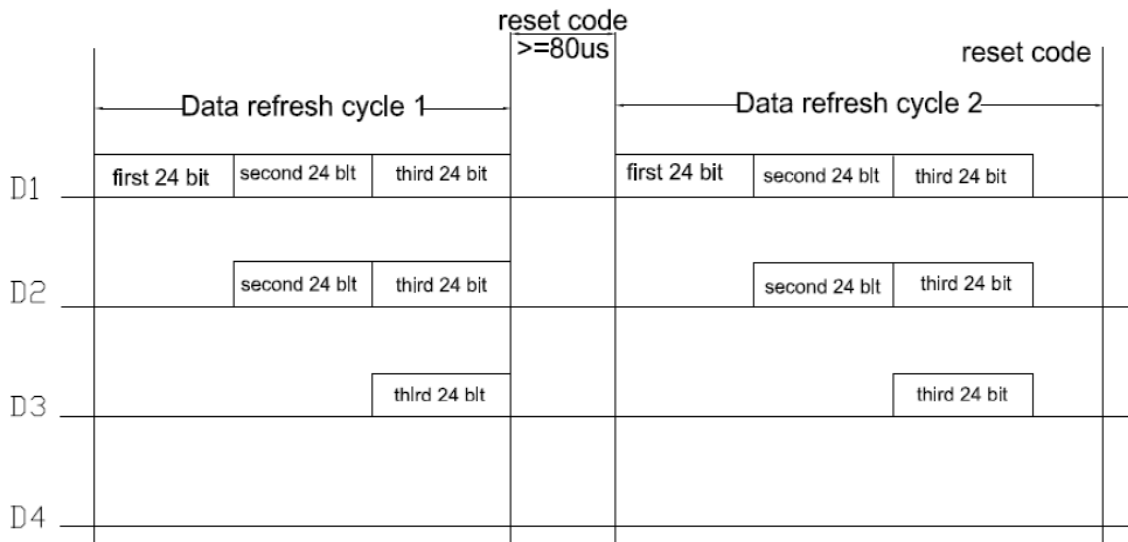
2. The data transmission time ( $T_H+T_L=1.25\mu s\pm 600ns$ ):

Name	Description	Typ. value	error
T0H	0 code, high level time	0.3 $\mu s$	$\pm 0.15\mu s$
T0L	0 code, low level time	0.9 $\mu s$	$\pm 0.15\mu s$
T1H	1 code, high level time	0.9 $\mu s$	$\pm 0.15\mu s$
T1L	1 code, low level time	0.3 $\mu s$	$\pm 0.15\mu s$
Trst	Reset code, low level time	80 $\mu s$	

3. Connection Mode

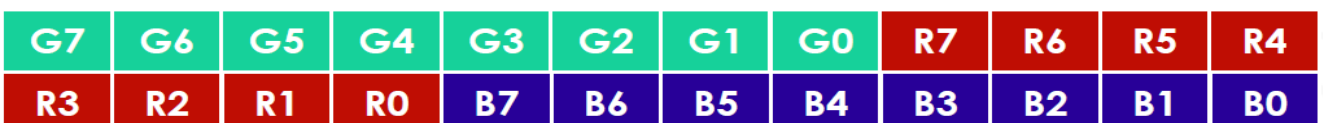


4. The method of data transmission

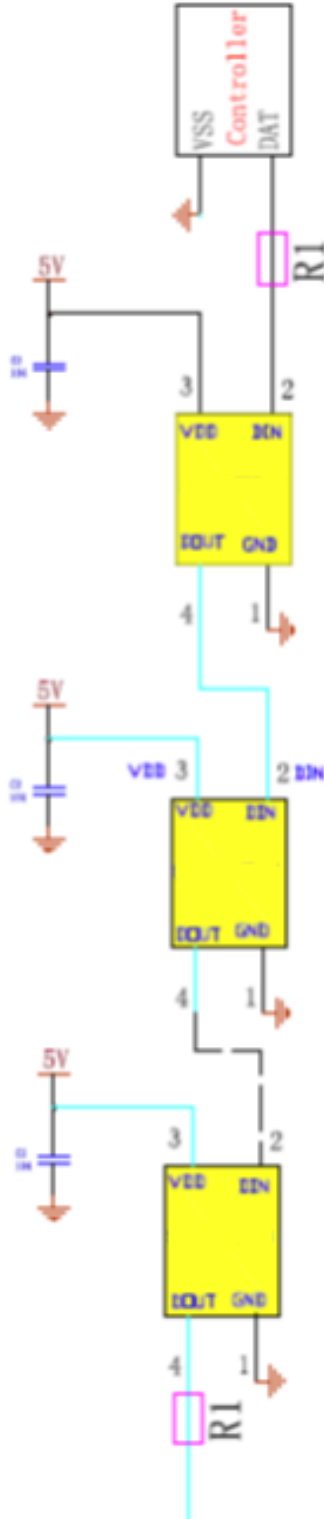


Note: the D1 sends data for MCU, D2, D3, D4 for data forwarding automatic shaping cascade circuit.

5. 24-bit data format

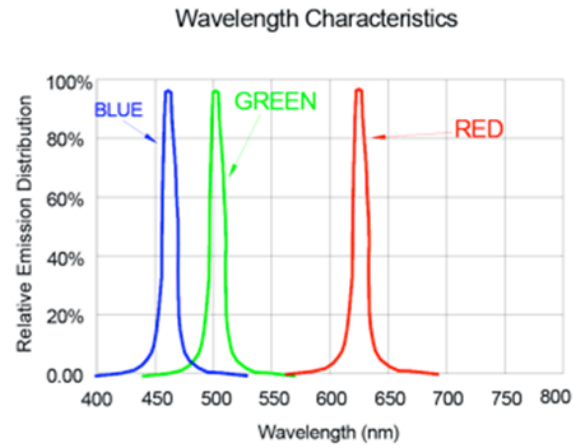
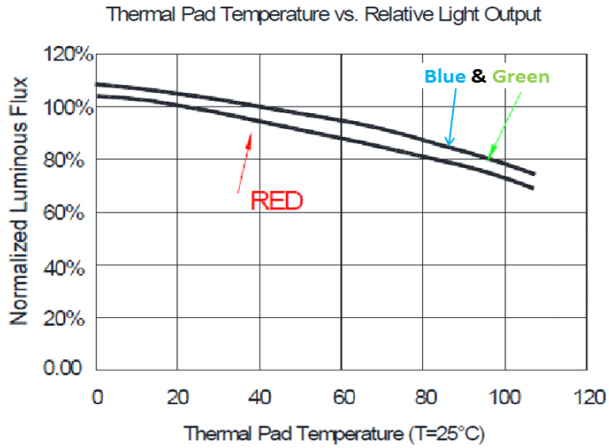


Note: high starting, in order to send data (G7 - G6 - ..... -B0)

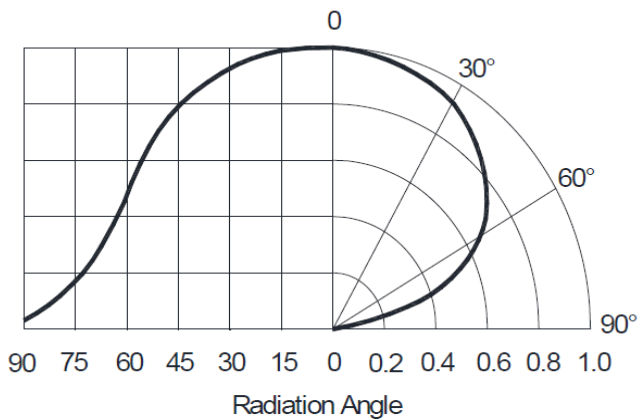
**Typical Application Circuit**


Product signal input and output must be connected in series with protection resistor R1. R1 depends on the size of the cascade amount, the greater the number of cascade, the smaller R1. The general recommended value is between 200-2K $\Omega$ , usually the recommended value is typical 500 $\Omega$ .

## LED Performance Graph



Typical Radiation Pattern 120°

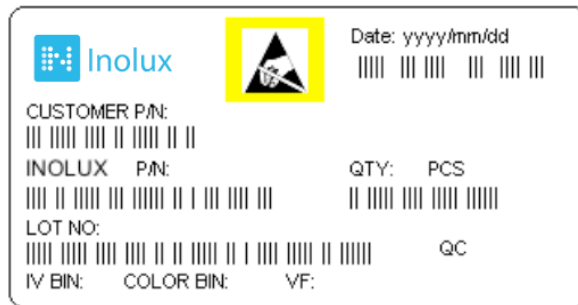




### Ordering Information

Product	Emission Color	IV(mcd)	Orderable Part Number
IN-PI22TAT5R5G5B	R	100-200	IN-PI22TAT5R5G5B
	G	400-700	
	B	50-100	

### Label Specifications



### Inolux P/N:

I	N	PI	-	22	T	A	T	(X)	R	(X)	G	(X)	B	-	X	X	X	X
Inolux		Product		Package	Die Qty.	Variation	Orientation	Current	Color	Current	Color	Current	Color		Customized Stamp-off			
		PI- Single trace IC PC- Clock Function IC		22TA = 24 x 27 x 1.1 mm			T = Top Mount	P=12mA 5 = 5mA	R = 624 nm	P=12mA 5 = 5mA	G = 520 nm	P=12mA 5 = 5mA	B = 470 nm					

### Lot No.:

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Internal Tracker	Year (2017, 2018, .....)				Month	Date	Serial

## Precautions

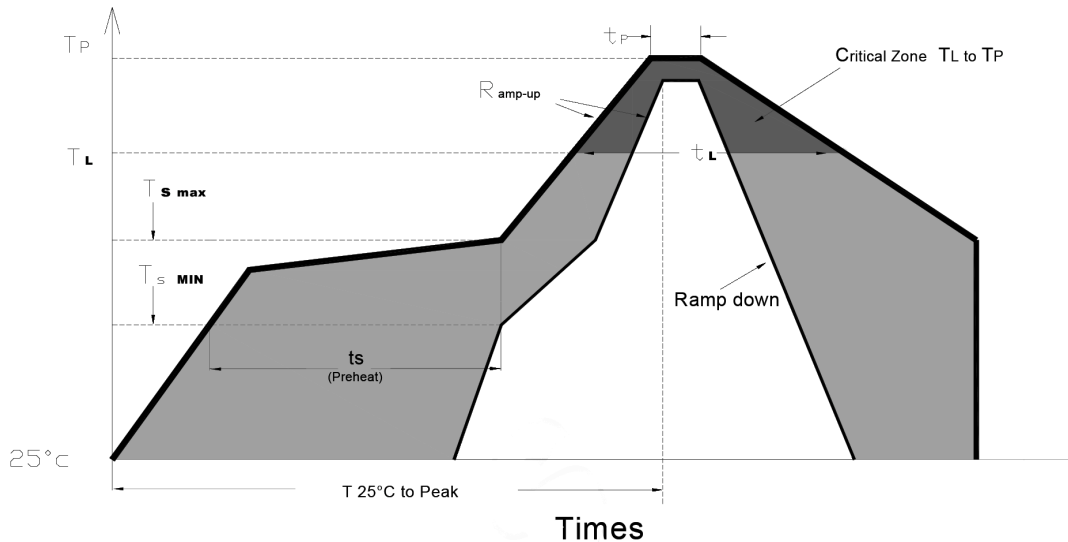
Please read the following notes before using the product:

### 1. Storage

- 1.1 Do not open moisture proof bag before the products are ready to use.
- 1.2 Before opening the package, the LEDs should be kept at 30°C or less and 80%RH or less.
- 1.3 The LEDs should be used within a year.
- 1.4 After opening the package, the LEDs should be kept at 30°C or less and 60%RH or less.
- 1.5 The LEDs should be used within 24 hours (1 days) after opening the package.
- 1.6 If the moisture adsorbent material has fabled away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions. Baking treatment: 60±5°C for 24 hours.

## 2. Soldering Condition

Recommended soldering conditions:



Profile Feature	Lead-Free Solder
Average Ramp-Up Rate ( $T_{s \max}$ to $T_p$ )	3°C/second max.
Preheat: Temperature Min ( $T_{s \min}$ )	150°C
Preheat: Temperature Min ( $T_{s \max}$ )	200°C
Preheat: Time ( $t_{s \min}$ to $t_{s \max}$ )	60-180 seconds
Time Maintained Above: Temperature ( $T_L$ )	217 °C
Time Maintained Above: Time ( $t_L$ )	60-150 seconds
Peak/Classification Temperature ( $T_p$ )	240 °C
Time Within 5°C of Actual Peak Temperature ( $t_p$ )	<10 seconds
Ramp-Down Rate	6°C/second max.
Time 25 °C to Peak Temperature	<6 minutes max.

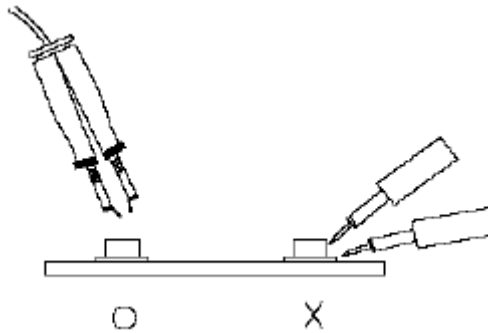
Note: Excessive soldering temperature and / or time might result in deformation of the LED lens or catastrophic failure of the LED.

### 3. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 260°C for 5 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

### 4. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



### 5. Caution in ESD

Static Electricity and surge damages the LED. It is recommended to use a wristband or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.

## Revision History

Changes since last revision	Page	Version No.	Revision Date
Initial Release		1.0	05-31-2018
Format Adjustment		1.1	07-01-2018

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